

IN THE CLAIMS:

Claim 1 (currently amended): A reflow soldering apparatus comprising a conveyor to transport circuit boards mounted with electronic components into multiple chambers, and blowing means installed in said chambers, wherein the centers of the impellers in said adjacent blowing means are not on a single perpendicular plane along a transport line of said conveyor and arrayed offset to the left and right, and said adjacent blowing means are installed to overlap as seen horizontally from a direction perpendicular to the transport line of said conveyor.

Claim 2 (original): A reflow soldering apparatus as claimed in claim 1, wherein said blowing means are arrayed left and right in a zigzag pattern along the transport line of said conveyor.

Claim 3 (currently amended): A reflow soldering apparatus comprising a conveyor to transport circuit boards mounted with electronic components into multiple chambers, and blowing means installed in said chambers, wherein the centers of the impellers in said adjacent blowing means are not on a single horizontal plane and arrayed offset up and down, and said adjacent blowing means are installed to overlap as seen vertically from a direction perpendicular to the transport line of said conveyor.

Claim 4 (original): A reflow soldering apparatus as claimed in claim 3, wherein said blowing means are arrayed above and below in a zigzag pattern along the transport line of said conveyor.

Claims 5-7 (canceled):

Claim 8 (new): A reflow soldering apparatus comprising a conveyor to transport circuit boards mounted with electronic components into multiple chambers, and blowing means installed in said chambers, wherein the centers of the impellers in said adjacent blowing means are not on a single perpendicular plane along a transport line of said conveyor and arrayed offset to the left and right, and blowing means storage sections of the adjacent casing members of said blowing means are installed to overlap as seen horizontally from a direction perpendicular to the transport line of said conveyor.

Claim 9 (new): A reflow soldering apparatus as claimed in claim 8, wherein said blowing means are arrayed left and right in a zigzag pattern along the transport line of said conveyor.

Claim 10 (new): A reflow soldering apparatus comprising a conveyor to transport circuit boards mounted with electronic components into multiple chambers, and blowing means installed in said chambers, wherein the centers of the impellers in said adjacent

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blowing means are not on a single horizontal plane and arrayed offset up and down, and blowing means storage sections of the adjacent casing members of said blowing means are installed to overlap as seen vertically from a direction perpendicular to the transport line of said conveyor.

Claim 11 (new): A reflow soldering apparatus as claimed in claim 10, wherein said blowing means are arrayed above and below in a zigzag pattern along the transport line of said conveyor.